# ICVISP 2026

# 2026年第十届 视觉、图像与信号处理国际会议

2026年12月11-13日 | 中国·海口

2026 10th International Conference on Vision, Image and Signal Processing

## Welcome to ICVISP 2026

It is with great pleasure that we invite you to the 2026 10th International Conference on Vision, Image and Signal Processing (ICVISP 2026), which is organized by **Hainan University**, co-organized by **School of Computer Science, Hubei University**, **School of Electronics and Information Engineering, Anhui University**, and **Key Laboratory of Underwater Acoustic Communication and Marine Information Technology Ministry of Education**. It is scheduled to take place from December 11-13, 2026, in Haikou, China.

ICVISP is committed to delivering a platform for collaboration and discovery, with the aim of driving progress in image, vision, and signal processing—key technologies that are enhancing our understanding of the world and propelling advancements in artificial intelligence, machine learning, and a multitude of other applications that are transforming industries and improving lives.

We warmly invite your contributions and eagerly anticipate the opportunity to meet with you in person at ICVISP 2026.

## Organizing Committee

**General Chair**
Xianpeng Wang, Hainan University, China

**Conference Chairs**
Yang Yue, Xi'an Jiaotong University, China
Fangqing Wen, China Three Gorges University, China

**General Co-chair**
Ting Su, Hainan University, China

**Program Chairs**
Zhenjia Chen, Hainan University, China
Hao Tang, Hainan University, China
Han Wang, Yichun University, China

**Publication Chairs**
Guilu Wu, Hainan University, China
Mingcheng Fu, Hainan University, China

**Local Chairs**
Yuanyuan Wu, Hainan University, China
Kun Zhang, Hainan Normal University, China
Jinmei Shi, Hainan Vocational University of Science and Technology, China
Jicheng Kan, Hainan Vocational University of Science and Technology, China

**Publicity Chairs**
Yuehao Guo, Hainan University, China
Bo Xu, Hainan University, China

**Finance Chairs**
Yongqin Yang, Hainan University, China
Xiang Lan, Hainan University, China

**Award Chair**
Jilin Zhu, Hainan University, China

**Program Committee**
Kang Su, Hainan University, China
Kuo Chi, Hainan University, China
Gan Luan, Hainan University, China
Yan Zhao, Hainan University, China
Hanyang Shi, Hainan University, China

## Keynote Speakers



**Prof. Mingyi He**
Northwestern Polytechnical University, China



**Prof. Guangzhi Wang**
Tsinghua University, China



**Prof. Tae-Kyun (T-K) Kim**
KAIST AGI Research Institute, South Korea



**Prof. Sung-Bae Cho**
Yonsei University, South Korea



**Prof. Renwei Dian**
Hunan University, China

## Topics of Interest

For more information, please visit: www.icvisp.org/cfp.html

**Computer Vision**
- 3D Computer Vision
- Adversarial Attack and Defense

**Image Processing**
- Synthesis, Rendering, & Visualization
- Computational Imaging

**Signal Processing**
- Applied Signal Processing Systems
- Audio & Acoustic Signal Processing

**Multimodal AI**
- Multimodal Data Modeling
- Multimodal Data Fusion

**Applications**
- Augmented and Mixed Reality
- Autonomous Driving

## Submission

- Manuscripts submitted to the conference should be written in English only.
- Manuscripts submitted to the conference should follow the template provided.
- Manuscripts can be submitted in Doc, Docx and PDF format.
- Oral or Poster presentations should be nominated while submitting an abstract.
- The ordinary length is suggested no less than 5 pages, including all figures, tables, references, and appendices. If the paper exceeds 8 pages, the additional pages will be charged at the time of registration.

For paper template, please visit: www.icvisp.org/sub.html
Online Submission link: https://cmt3.research.microsoft.com/ICVISP2026

## Tracks

For more information, please visit: www.icvisp.org/tracks.html

**Track I** : The Application of Artificial Intelligence in the Field of Meteorology

**Track II** : Advances in Hyperspectral Data Analysis and Processing

**Track III**: Multi-Modal Perception and Affective Computing

**Track IV** : Signal Analysis, Feature Extraction and Intelligent Recognition

**Track V** : Biologically Inspired Vision and Image Processing

**Track VI**: Advances in Low-Altitude and Maritime Target Detection and Environmental Sensing

**Track VII**: Deep Models for Aerial Robotics: Perception, Reasoning, and Edge Computing

**Track VIII** : Intelligent MIMO Radar Sensing: Target Detection, Imaging, and Multimodal Recognition

**Track IX**: Image Recognition Technology and Intelligent Driving

**Track X** : Weak and Small Object Recognition: Multimodal Perception, Robust Detection, and Edge Intelligence

**Track XI** : Vision-Driven Digital Twins: 3D/4D Reconstruction, Multimodal Data Fusion, and Physical–Virtual Synchronization

**Track XII**: Medical Image and Signal Processing

**Track XIII**: Advances and Frontier Application in Intelligent Remote Sensing Interpretation

**Track XIV**: Embodied Visual Perception: From Passive Recognition to Proactive Understanding

## Publication

Registered and presented full papers will be included in the ICVISP 2026 digital conference proceedings, which will be published by SPIE and submitted to major citation databases (including, but not limited to Ei Compendex and Scopus) for review and indexing.

SPIE. Compendex on Engineering Village Scopus

## Key Dates (Final Round)

Camera-ready Submission Due: November 22, 2026
Main Conference: December 11-13, 2026

## Publication History

**ICVISP 2017 | Osaka, Japan**
Published by IEEE
ISBN: 978-1-5386-0612-4
EI Compendex & Scopus

**ICVISP 2018 | Las Vegas, USA**
Published by ACM
ISBN: 978-1-4503-6529-1
EI Compendex & Scopus

**ICVISP 2019 | University of British Columbia**
Published by ACM
ISBN: 978-1-4503-7625-9
EI Compendex & Scopus

**ICVISP 2020 | Virtually**
Published by ACM
ISBN: 978-1-4503-8953-2
EI Compendex & Scopus

**ICVISP 2021 | Virtually**
Published by IEEE
ISBN: 978-1-6654-0770-0
EI Compendex & Scopus

**ICVISP 2022 | Virtually**
Published by IOP JPCS
ISSN: 1742-6596
EI Compendex & Scopus

**ICVISP 2023 | Dali, China**
Published by IET
ISBN: 978-1-83724-014-2
EI Compendex & Scopus

**IEEE ICVISP 2024 | Kunming, China**
Published by IEEE
ISBN: 979-8-3315-4146-0
EI Compendex & Scopus

**ICVISP 2025 | Xi'an, China**
Published by IEEE
ISBN: 979-8-3315-5682-2
EI Compendex & Scopus

**Contact Info** www.icvisp.org inquiry@icvisp.org +028-85027305 (Mainland) +86-28-85027305 (International)